

International Journal of

Embedded Systems

Editor-in-Chief:
Prof. Kuan-Ching Li

**Visit www.inderscience.com/ijes
for more information and sample articles**



© 2014 Inderscience Enterprises Ltd



Scope of the Journal

ISSN: 1741-1068 (Print), ISSN: 1741-1076 (Online)

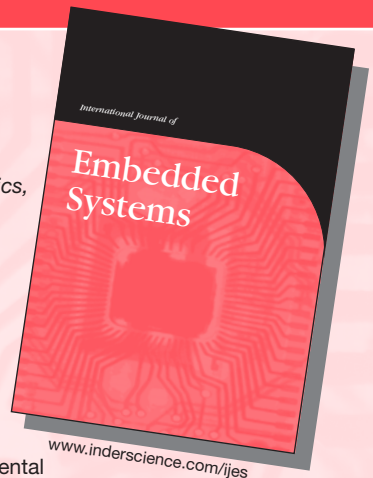
Embedded systems are increasingly becoming a key technological component of all kinds of complex technical systems, ranging from vehicles, telephones, audio-video equipment, aircraft, toys, security systems, medical diagnostics, to weapons, pacemakers, climate control systems, manufacturing systems, intelligent power systems etc. IJES addresses the state of the art of all aspects of embedded computing systems with emphasis on algorithms, systems, models, compilers, architectures, tools, design methodologies, test and applications.

Contents:

IJES is a refereed international journal providing an international forum to report, discuss and exchange experimental or theoretical results, novel designs, work-in-progress, experience, case studies, and trend-setting ideas. Papers should be of a quality that represents the latest advances in embedded systems in time-to-market, cost, code size, weight, testability, power, real-time behaviour, and stimulating future trends.

Topics covered include:

- Embedded system architecture
- Embedded software
- Embedded hardware
- Application-specific processors/devices
- Real-time systems
- Hardware/software co-design
- Testing techniques
- Industrial practices, benchmark suites
- Education
- Emerging technologies/applications/principles



Not sure if this title is the one for you?

Visit the journal homepage at www.inderscience.com/ijes where you can:

- View sample articles in full text HTML or PDF format
- Sign up for our free table of contents new issue alerts via e-mail or RSS
- View editorial board details
- Find out about how to submit your papers
- Find out about subscription options, in print, online or as part of a journals collection

You can order online at www.inderscience.metapress.com or download an order form from www.inderscience.com/subform.

This title is part of the Science, Engineering and Technology Collection (see www.inderscience.com/set). For library collection subscriptions or for a free institutional online trial, please contact subs@inderscience.com.